Supporting Information

Fabrication of High-к Dielectric Metal Oxide Films on Topographically Patterned Substrates: Polymer Brush Mediated Depositions

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* Corresponding author: * E-mail: <u>pyadav@tcd.ie</u> (P.Y.) <u>morrism2@tcd.ie</u> (M.A.M.) The upper threshold temperature for polymer brush grafting was determined using thermogravimetric analysis of powder P4VP-OH. We set a grafting temperature of 230 °C, to achieve complete monolayer coverage of the polymer brush.



Figure S1 Thermogravimetric analysis was performed on the 5.5 kmol⁻¹ P4VP-OH at temperature range of 25-600°C for 60 minute. Polymer undergo thermal degradation at 250°C indicating optimum temperature for the grafting process.



Figure S2 (a) water contact angle angle of grafted P4VP polymer brush measured at plane region of topographically patterned substrate of thick-coated P4VP film on plane silicon substrate (b) water contact angle of thick-coated P4VP film on plane silicon substrate (c) water contact angle of P4VP homopolymer pressed pellet using hydraulic pressure.



Figure S3 AFM image of **(a)** as receive silicon native oxide substrate with line images at L1. **(b)** AFM and SEM images of P4VP polymer grafted silicon substrates with line images at L2 **(c and d)** are AFM and SEM images of oxidised ZrO_2 and HfO_2 samples with line images at L3 and L4